Materials Declaration

Package	MINI_SO
Body Size	
LeadCount	8
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.1	1.09 E-02	434876
Epoxy resin	7.5	9.53 E-04	37881
Phenol Novolac	4.0	5.08 E-04	20203
Sb2O3	1.5	1.91 E-04	7576
Brominated resin	0.6	7.62 E-05	3030
Carbon black	0.3	3.81 E-05	1515
Subtotal		1.27 E-02	505083

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.57	9.76 E-03	387983
Fe	2.28	2.28 E-04	9062
Zn	0.13	1.26 E-05	502
P	0.02	2.42 E-06	96
Subtotal		1.00 E-02	397643

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.01 E-04	4017

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.55 E-04	26047

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.10 E-04	12328

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.00 E-03	39770

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	3.04 E-04	12090
Resin	20	5.70 E-05	2267
Aromatic Amine	5	1.90 E-05	756
Subtotal		3.80 E-04	15113

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Package Totals

Weight (g)	PPM
2.51 E-02	1000000

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ADI Proprietary

Materials Declaration

Package	MINI_SO
Body Size	
LeadCount	8
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.1	1.09 E-02	434098
Epoxy resin	7.5	9.53 E-04	37813
Phenol Novolac	4.0	5.08 E-04	20167
Sb2O3	1.5	1.91 E-04	7563
Brominated resin	0.6	7.62 E-05	3025
Carbon black	0.3	3.81 E-05	1513
Subtotal		1.27 E-02	504179

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.57	9.76 E-03	387289
Fe	2.28	2.28 E-04	9046
Zn	0.13	1.26 E-05	501
P	0.02	2.42 E-06	96
Subtotal		1.00 E-02	396932

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.01 E-04	4010

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	5.95 E-04	23621
Pb	15.0	1.05 E-04	4168
Subtotal		7.00 E-04	27789

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.10 E-04	12306

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.00 E-03	39699

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	3.04 E-04	12069
Resin	20	5.70 E-05	2263
Aromatic Amine	5	1.90 E-05	754
Subtotal		3.80 E-04	15086

Package Totals

Weight (g)	PPM
2.52 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS

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Materials Declaration

Package	MINI_SO - COL
Body Size	
LeadCount	8
Option	NiPdAu

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	87.7	1.11 E-02	454800
Epoxy resin	5.0	6.35 E-04	25929
Phenol Resin	5.0	6.35 E-04	25929
ECN	2.0	2.54 E-04	10372
Carbon Black	0.3	3.81 E-05	1556
Subtotal		1.27 E-02	518587

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	9.73 E-03	397270
Fe	2.35	2.28 E-04	9304
Zn	0.12	1.26 E-05	516
P	0.03	2.42 E-06	99
Subtotal		9.97 E-03	407189

Internal/External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ni	100	1.16 E-04	4743
Pd	100	1.01 E-05	412
Au	100	1.52 E-06	62
Subtotal		1.28 E-04	5217

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.10 E-04	12657

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.00 E-03	40834

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Epoxy Resin	31	1.18 E-04	4810
Metal Oxide	31	1.18 E-04	4810
Glycol Ethers	22	8.36 E-05	3414
Silica	8	3.04 E-05	1241
Curing agent & hardener	8	3.04 E-05	1241
Subtotal		3.80 E-04	15517

Molding Compound

Item	PPM	Method
Pb	Not Detected	USEPA 3050B. ICP-OES.
Cd	Not Detected	EN1122 Method B:2001. ICP-OES.
Hg	Not Detected	USEPA 3052. ICP-OES.
Cr+6	Not Detected	EPA 3060A/7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550B. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550B. GC/MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cd	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Hg	Not Detected	Draft IEC62321. EPA Method 3052. ICP-OES.
Cr+6	Not Detected	Draft IEC62321. EPA Method 3060A. UV-VIS.
PBB	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.
PBDE	Not Detected	Draft IEC62321. EPA Method 3540C. GC/MS-D.

Package Totals

Weight (g)	PPM
2.45 E-02	1000000

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